

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Se Bum SON	12/26/2007
Sung Hee AHN	12/26/2007
In Hwan OH	12/26/2007
Sung Duk HWANG	12/26/2007
RECEIVING PARTY DATA	
Name:	Cheil Industries Inc.
Street Address:	290 Gongdan-dong
Internal Address:	Gumi-si
City:	Gyeongsangbuk-do
State/Country:	REPUBLIC OF KOREA
Postal Code:	730-710
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11965013
CORRESPONDENCE DATA	
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
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ATTORNEY DOCKET NUMBER:	6250.049
NAME OF SUBMITTER:	Melissa B. Pendleton

OP \$40.00 11965013

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REEL: 020293 FRAME: 0362

Total Attachments: 4

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PATENT

REEL: 020293 FRAME: 0363

ASSIGNMENT

WHEREAS, I, Se Bum SON, a Korean citizen, residing at 130-1202, Hanyang Saebyeul Apt., Dalan-Dong, Dongan-Gu, Anyang-Si, Gyeonggi-do, Republic of Korea; Sung Hee AHN, a Korean citizen, residing at 103-102 Gumho bestville, 1052 Hawangsimni-Dong, Seongdong-Gu, Seoul, Republic of Korea; In Hwan OH, a Korean citizen, residing at #201, 812-5, Naeson1-Dong, Uiwang-Si, Gyeonggi-do, Republic of Korea; and Sung Duk HWANG, a Korean citizen, residing at 101-1201 Lotte Castle Park, 835, Sungsool-Ga, Sungdong-Gu, Seoul (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Thermoplastic Resin Composition Having Improved Impact Resistance*, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from a Korean application filed on December 29, 2006, under Serial No. 2006-138889, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Cheil Industries Inc., a Korean corporation (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 290 Gongdan-dong, Gumi-si, Gyeongsangbuk-do 730-710, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

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REEL: 020293 FRAME: 0364

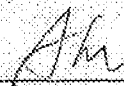
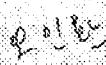
NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest—in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute

any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

<u>Dec 26th</u> , 2007	 Se Bum SON
<u>Dec. 26th</u> , 2007	 Sung Hee AHN
<u>Dec. 26th</u> , 2007	 In Hwan OH
<u>Dec. 26th</u> , 2007	 Sung Duk HWANG

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